

DATA SHEET

Revise History

Rev.	Descriptions	Date	Page
1.0	-	23-10-2009	-
2.0	Renew form	15-12-2015	-
2.1	Renew form	10-11-2018	-
2.2	Renew form	27-12-2021	-
2.3	Renew form	23-10-2023	-
2.4	Renew form	10-12-2024	-



Features

- Long operating life.
- Low Power Consumption.
- Low voltage DC operated.
- RoHS Compliant.

Application

- Infrared Illumination for cameras.
- Machine vision systems.
- Surveillance systems,Industrial electronics.
- IR data transmission,Remote control.

Part Number	Dice Material	Emitted Color	Lens Color
IE-5IR4PRC-10	GaAlAs	Infrared	Water Clear

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity	Ee	150	300	-	mW/sr	IF=50mA
Forward Voltage	VF	-	1.50	1.80	V	IF=50mA
Radiation Bandwidth	$\Delta\lambda$	-	45	-	nm	
Peak Wavelength	λ_p	840	850	860	nm	
Viewing Angle ^{*1}	2 θ 1/2	5	-	10	deg	
Reverse Current	IR	-	-	5	uA	VR=10V

Notes :

1.2 θ 1/2 is the o-axis angle where the luminous intensity is 1/2 the peak intensity.

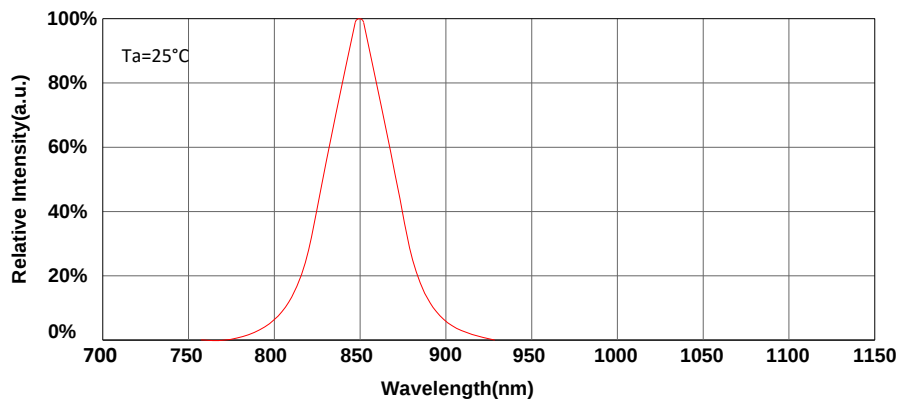
Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Max.	Unit
		Infrared	
Power Dissipation	Pd	180	mW
Peak Forward Current ^{*1}	IFP	1000	mA
Forward Current	IF	100	mA
Human Body Model	ESD	2000	V
Operating Temperature Range	Topr	-40to+85	℃
Storage Temperature Range	Tstg	-40to+90	℃
Wave Soldering	Tsld	260℃ for 5 secs	

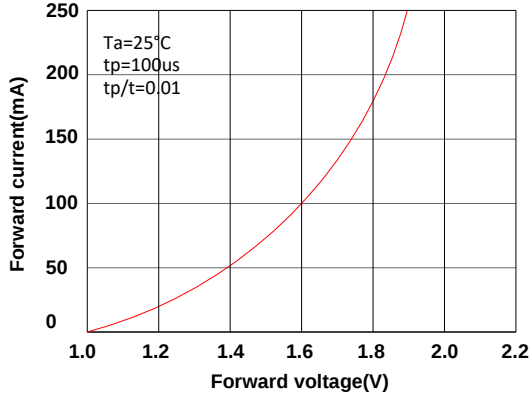
Notes : 1.Duty Factor=10%, Frequency=1kHz.

Optical & Electrical Characteristics Curves

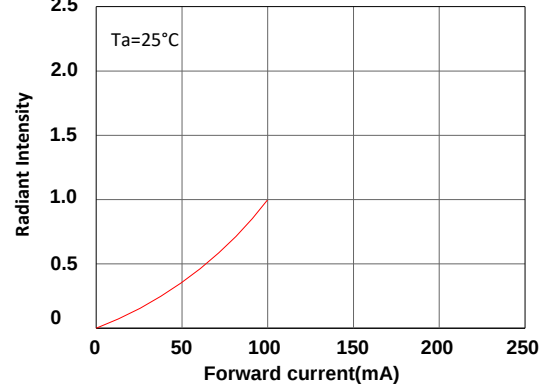
Relative Intensity vs.Wavelength



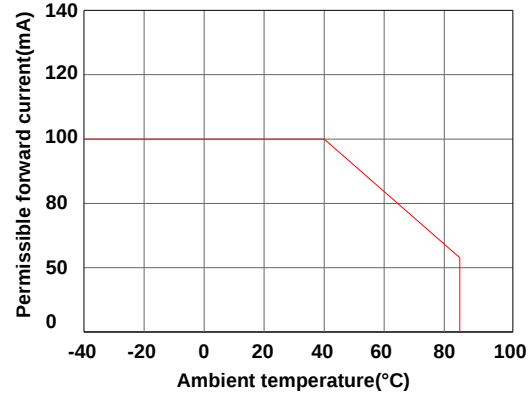
Forward Current vs.Forward Voltage



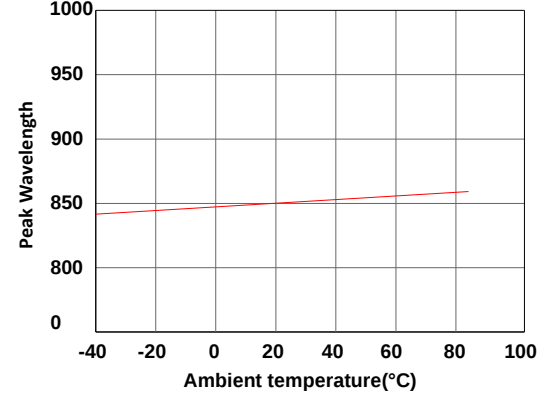
Radiant Intensity vs. Forward Current



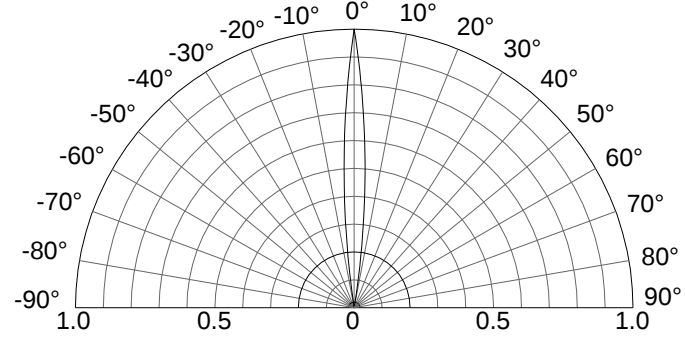
Forward Current Derating Curve



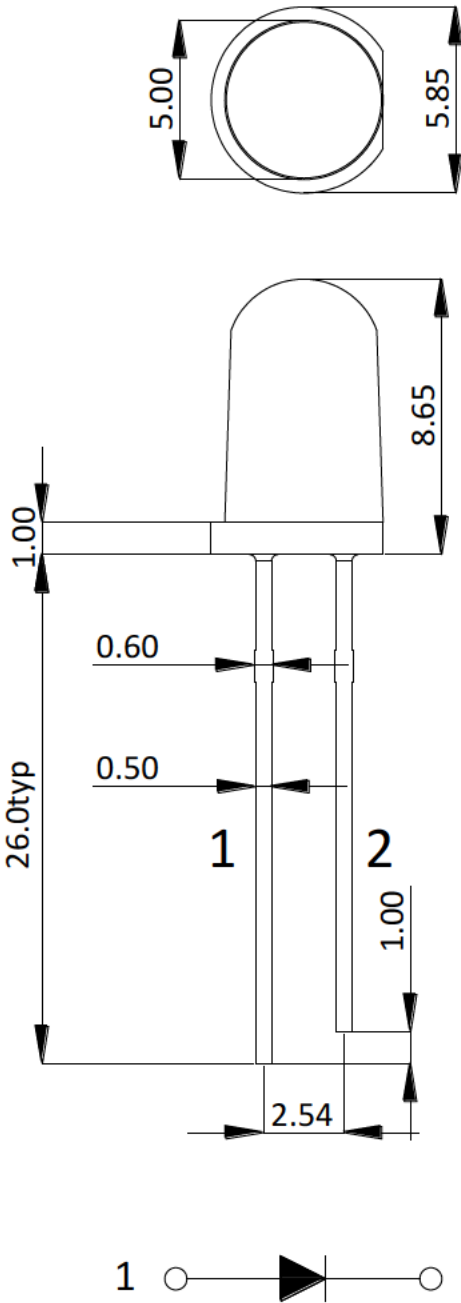
Peak Wavelength vs.Ambient Temperaturs



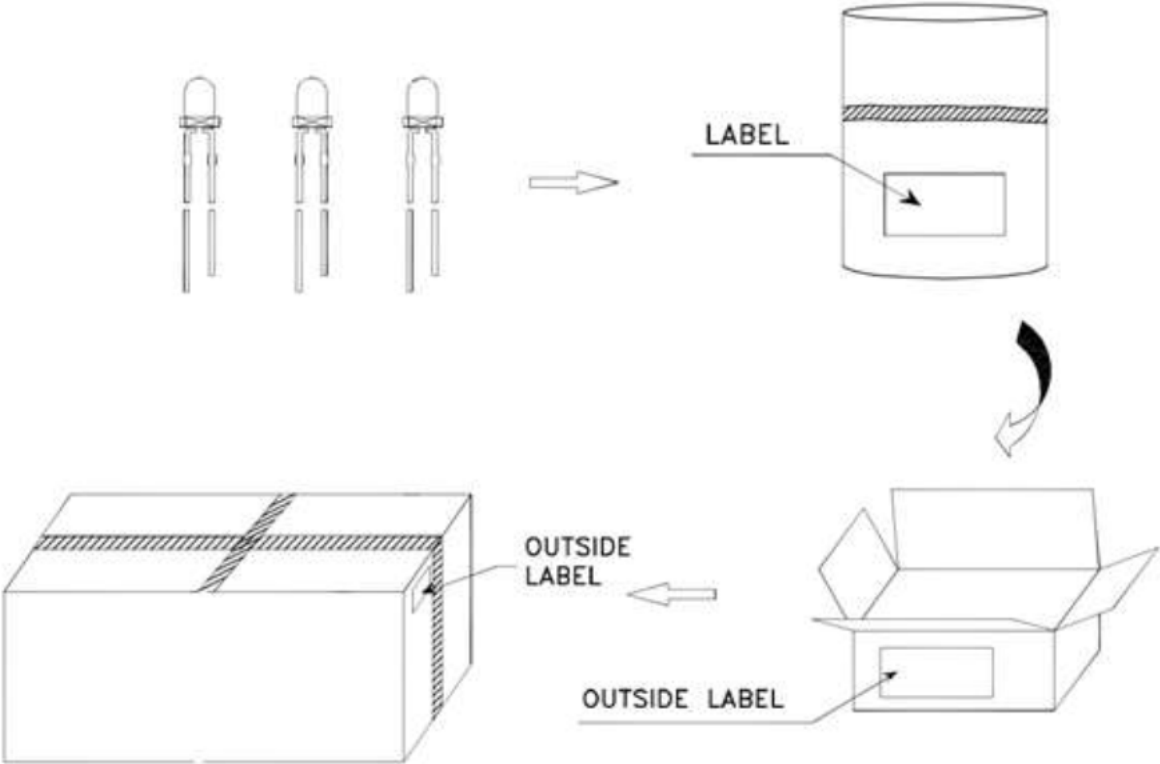
Spatial Distriution



Package Dimension (Unit:mm,Tolerance:±0.20mm)



Packaging method



Packing Quantity:500 PCS/bag.

Precautions

1. Lead Forming

1.1 During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.

1.2 Lead forming should be done before soldering.

1.3 Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.

1.4 Cut the LED lead frames at room temperature. Cutting the lead frames at high temperatures may cause failure of the LEDs.

1.5 When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

2. Storage

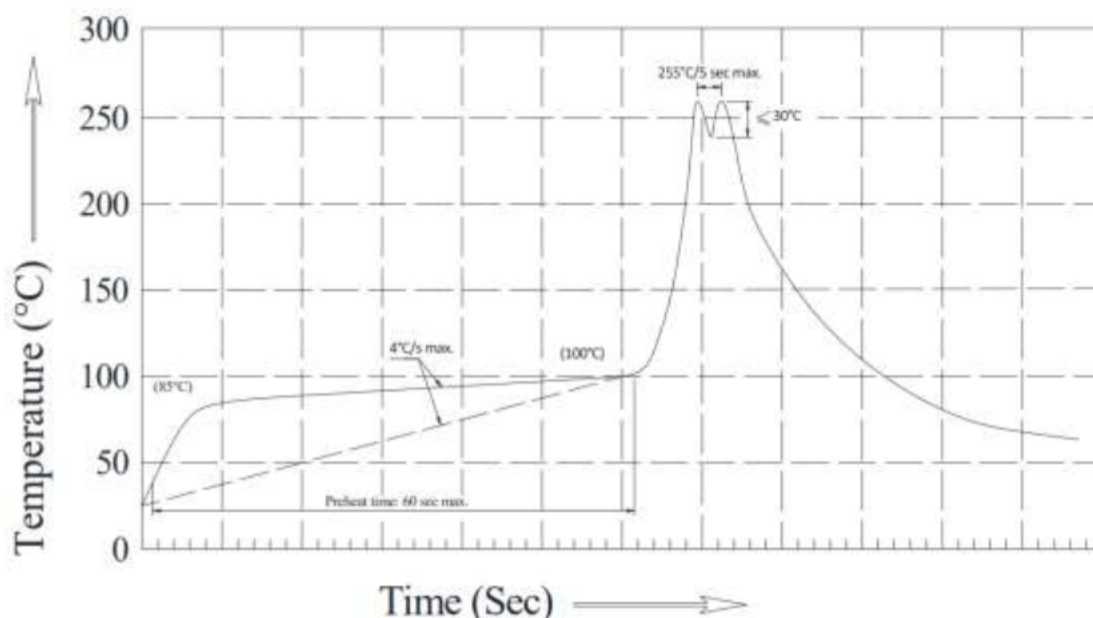
2.1 The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from ekinglux and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.

2.2 Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

3. Soldering

3.1 Careful attention should be paid during soldering. When soldering, leave more than 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.

3.2 Recommended Wave Soldering Profiles



Note :

1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C.

2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

3.3 Recommended soldering conditions :

Soldering Iron		Wave Soldering	
Temperature	300°C Max.	Pre-heat	100°C Max.
Soldering Time	3 sec. Max. (one time only)	Pre-heat Time	60 sec. Max.
		Solder Wave	260°C Max.
		Soldering Time	5 sec. Max.

Note :
Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

3.4 Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.

3.5 Dip and hand soldering should not be done more than one time

3.6 After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.

3.7 A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

3.8 Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the LEDs.

3.9 Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

4. Cleaning

4.1 When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.

4.2 Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED.

5. Assembly method

The spacing between LED leadframe must match the spacing between mounting holes on the PCB when placing components. If LED leadframe need to be formed to ensure that the spacing between leadframe matches the spacing between PCB holes.